CTC-035 Moisture Sensitivity Level (MSL-1 on SOT23 package)

Statement Date: 4-15-23

Overview

As we know, the components with plastic-body package are all sensitive to both the moisture and temperature. Moisture can penetrate package and may lead to internal crack and delaminating when the components pass through the reflow process. Meanwhile, due to lead-free (Sn) soldering requires higher soldering temperature (peak reflow temperature) than Sn Pb soldering, the components have to be tested and classified moisture sensitivity level will be during varied lead-free soldering temperature.

The JEDEC standard J-STD-020E – Moisture/Reflow Sensitivity Classification for Non-hermetic Surface Mount Devices describes soak and test conditions to classify parts.

Moisture Sensitivity Level	Floor Life	
	Time	Conditions
1	Unlimited	≤30°c /85% RH

MSL Classifications
J-STD-20

InterFET End Product Statement

InterFET Corporation sells JFET transistor products for use in many applications including commercial, industrial, and military. InterFET products storage and shipping conditions are unlimited for moisture impact to package and electrical performance.

InterFET works closely with its suppliers and reviews their certifications and material content used during the manufacturing process. Based on this information, InterFET has determined to the best of its knowledge that certain InterFET Corporation products are robust to environmental moisture and typical reflow parameters..

InterFET Product Manufacturing Statement

InterFET's JFET products are manufactured using a fabless business model with selected assembly operations for volume production.

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